

Design of A Programmable Bandgap Reference Circuit

Khadijeh Karamzadeh, Akaram Asghari Govar, Jafar Sobhi, Hamid Moharrami

Abstract—This paper describes the design of a programmable voltage bandgap reference, simulated in 0.35 μ m CMOS technology. This work is used for trimming and calibration process. The circuit generates a variable reference voltage of 1.2380 until 1.3051. It can operate with supply voltages between 3.0v and 3.6V and between 0C and 85C. It has a PSRR 56dB under normal operating conditions. This circuit works in a current feedback mode, and it generates its own reference current, resulting in a stable operation. A startup circuit is required for successful operation of the system.

Index Terms—Proportional To Absolute Temperature (PTAT), Conversely proportional To Absolute Temperature (CTAT), BandgapReference (BGR), Temperature Coefficient (TC).

1 INTRODUCTION

A KEY ELEMENT of analog-to-digital (A/D) and digital-to-analog (D/A) converters is a precise voltage reference with good temperature stability. Accurate biasing voltages are critical for many circuit schemes; in ADC, a reference voltage is required to quantify an input, while in DAC, it is required to define the output full-scale range. As a well-established reference generator technique, bandgap reference is most popular for both Bipolar and CMOS technologies.

The principle of the bandgap circuits relies on two groups of diode-connected BJT transistors running at different emitter current densities. By canceling the negative temperature dependence of the PN junctions in one group of transistors with the positive temperature dependence from a PTAT (proportional-to-absolute-temperature) circuit which includes the other group of transistors, a fixed DC voltage which doesn't change with temperature is generated.[3][4] There are many different implementation reported, while essentially a bandgap reference circuit consists of a supply independent biasing circuit, a diode connected BJT transistor generating a voltage with negative temperature coefficient, a PTAT circuit and some kind of feedback mechanism to improve the performance. This working principle of a bandgap voltage reference can be illustrated by Fig1 since V_{BE} decreases approximately linear with temperature while V_T increases linearly with temperature, a low-temperature-dependence V_{REF} can be obtained by scaling up V_T and summing it with V_{BE} .

The outline of this paper is as follows: in section II

circuit description is presented. Section III presents circuit

analysis units. In the section V, we demonstrated simulation result. The results were obtained by simulation produce in a 0.35 μ m processions form the last section.

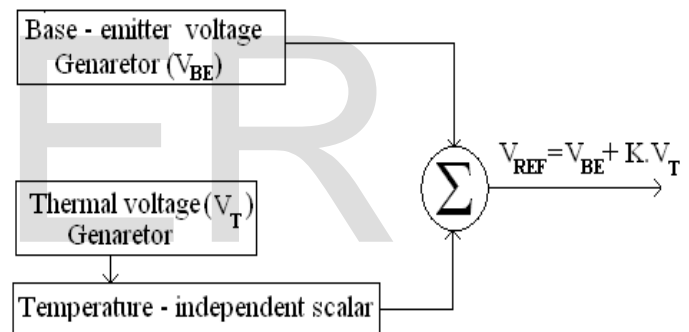


Fig. 1. Concept of bandgapVoltage Reference

2 CIRCUIT DESCRIPTION

Adding two voltages that have temperature coefficients of opposite sign with suitable multiplication constants generates a reference voltage. The resulting voltage obtained is independent of temperature. The diode voltage drop across the base-emitter junction, V_{BE} , of a Bipolar Junction Transistor (BJT) changes Complementarily to Absolute Temperature (CTAT) [1]. Whereas if two BJTs operate with unequal current densities, then the difference in the base emitter voltages, ΔV_{BE} , of the transistors is found to be Proportional to Absolute Temperature (PTAT). The PTAT relationship is given by [2],

$$\Delta V_{BE} = V_T \ln m; \quad V_T = kT/q \quad (1)$$

where, k is Boltzmann's constant, T is the absolute temperature, q is the electron charge and m is the ratio of the current densities of the two BJTs. The PTAT voltage may be added to the CTAT voltage with suitable

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It should be noted that in this section R_x is neglected. Fig.3 shows the block diagram of the variable badgap

reference circuit designed. By using a supply independent current source, a current I_{SS} is passed through BJT A. The same current I_{SS} flows through m transistors connected in parallel, identical to A. Thus the current density of A is m

It should be noted that an ideal BJT is not available in CMOS technology. A pnp BJT is made using the n-well normally associated with a PFET [1] the p-substrate behaving as the collector.

In order to generate supply independent current and carry out an addition of the CTAT and PTAT voltages, the circuit in Fig4 is used. The OPAMP provides the base voltage to the transistors, which are connected as current mirrors. By selecting the value of R1 and current ISS, the circuit may be designed to operate at the desired operating point. The value of R1 is given by,

Since the same current I_{SS} flows through R_2 , the voltage at the output reference voltage nodes is given by,

Thus by selecting the value of R2 the weighting constant may be set. This arrangement provided an elegant arrangement to generate the reference voltage while conserving voltage headroom. The circuit has a stable operating point at which no current flows through it. An arrangement must be made to force the saturation when the supply is turned on. The startup circuit carries out this function.

3.1 Bandgap Core

The bandgap reference voltage is generated by adding the base emitter voltage, V_{BE} , of a BJT to the difference in base emitter voltage, ΔV_{BE} of BJTs with a ratio of current density m . In order to generate a stable circuit, it is necessary to keep the BJT in the exponential region.

The change of the voltage of reference node is made possible by adding variable resistor in the base of Q1 and Q2 transistors. This method supplies the acceptable thermal characteristic to some extent (Fig4).

Ideally, the error amplifier has a high voltage gain A , and therefore $V_X = V_Y$ can be achieved, when $R_2 = R_3$,



$V_{DSTP1}=V_{DSTP2}$ can be easily obtained to provide a very good current matching by TP1 and TP2. V_{REF} can be generated by this structure without the need of an extra current branch. Both power consumption and errors can be reduced effectively.

The voltages X and Y are fixed by feedback, hence result the V_{REF} is given

$$V_{ref} = V_{BE} + I_{SS} \cdot R_2 + \frac{I_{SS}}{\beta} \cdot R_x \quad (4)$$

$$V_{ref} = V_{BE} + I_{SS} \left(R_2 + \frac{R_x}{\beta} \right) \quad (5)$$

$$V_{ref} = V_{BE} + \frac{\Delta V_{BE}}{R_1} \left(R_2 + \frac{R_x}{\beta} \right) \quad (6)$$

$$V_{ref} = V_{BE} + \left(\frac{R_2}{R_1} + \frac{R_x}{\beta R_1} \right) \cdot V_T \cdot \ln m \quad (7)$$

In the order achieve a zero temperature coefficient; the following equation must be satisfied.

$$\frac{\partial V_{ref}}{\partial T} = \left(\frac{R_2}{R_1} + \frac{R_x}{\beta R_1} \right) \ln m \cdot \frac{\partial V_T}{\partial T} + \frac{\partial V_{BE}}{\partial T} \quad (8)$$

$$\frac{\partial V_{ref}}{\partial T} = 0 \quad (9)$$

$$\Rightarrow \left(\frac{R_2}{R_1} + \frac{R_x}{\beta R_1} \right) \ln m \cdot \frac{\partial V_T}{\partial T} = - \frac{\partial V_{BE}}{\partial T} \quad (10)$$

The equation shows that R_1 , R_2 , R_x and m affect on the TC of V_{ref} . m is the ratio of the surface of Q1 and Q2 transistors. Because layouts on both BJTs and resistors should be well planned and designed so that consistent performance can be maintained with minimum need of trimming in mass productions. Better matching can be achieved by a common-centroid layout [6],[7]. However a large value of N is not preferred as the separation of devices increases, and this will introduce more errors. Moreover, as shown in (1) there is no signification increase on the $\ln(m)$ function when m increases.

For the resistor layout, common-centroid layout should be also used to obtain better matching[7]. Polysilicon is a better material than diffusion since its tempco is low. An even better material is high-resistive polysilicon, since it has a negative tempco. We used in the simulation.

As mentioned above, the amplitude of R_1 and m are set

before. Therefore only R_2 and R_x are affected in the thermal characteristic. If R_2 is much more than R_x/β , effect of the R_x in thermal characteristic would be neglected.

3.2 Opamp

The OPAMP was used to maintain equal node voltages and provide a feedback to maintain the drain currents constant and insensitive to supply variations. A high gain of the OPAMP would result in better voltage tracking of nodes X and Y

(Fig4). The common mode voltages play an important role in determining the OPAMP topology. The input common mode was determined by the base emitter voltage of the BJT, which is 0.8 V at 100 μ A of collector current. In order to meet the input common mode condition an active current mirror circuit with a PMOS driver was selected.

The output common mode voltage corresponds to the gate voltage of the current mirror transistors. In order to have a V_{DSAT} of 0.4 V for these transistors the output common mode should be ideally about 1.5 V. A second stage was added to the OPAMP to increase gain and shift the common mode voltage up by using an NMOS driver. The NMOS driver only provided an output common mode of about 0.4 V. By adding a diode-connected transistor, TN7, to the second stage, the output voltage was pushed up to about 1.3 V without any effect on the gain of the stage. The voltage drop across the diode connected transistor is about 1.2 V corresponding to $V_{TH} + V_{DSAT}$. The gain of each of the stages of the OPAMP is given by

$$A = g_m \cdot R_o \quad (11)$$

Where, A_v is the gain, g_m is the transconductance of the driving transistor and R_o is the effective output resistance at the output node.

3.3 Startup Circuit

Transistors TN1, TN2, TN3 and TP4 constitute the startup circuit. Initially all the transistors start off in off state. The voltage at the gate of TN1 is low and so it remains in off state. TP4 being diode connected is always on and so the transistor TN2 turns on forcing the drain to a low value. The current mirror stack turns on and the gate voltage of TN1 rises and it starts to conduct. At this point there is a competition between the output of the amplifier TP6, and TN2 for the current source load. TN2 is designed to be a weak transistor so the amplifier takes control of the current mirror gate.

When the bandgap voltage is high enough ($\sim 1V$) the transistor TN1 turns on. TN1 in linear region has to compete with TN2 in saturation so it is designed to be a big transistor. It draws all the current from TP2 and the base voltage of TN2 falls till it turns off. In this state the gate voltage at TN2 is about 0.6 V. This is high enough for the transistor TN1 to be conduct slightly. A diode connected transistor TN3 is added to increase the threshold voltage at the gate of TN3 to turn off. The transistor TP4 is designed to be a weak device

so that low current flows through the parasitic path when the circuit is in full operation.

4 RESULTS

The variable bandgap reference voltage gives a voltage of 1.2672V when adjusted to have a zero temperature coefficient at 27°C when R_x is 900 Ω . Fig5 shows the result of the simulation. As can be seen an overall temperature coefficient of 0.0141mV/K is obtained between 0°C and 85°C, which corresponds to about 0.0946% variation. The response it worse for temperatures from 64-85°C with a temperature coefficient of 0.0571mV/K. Below these temperatures the temperature coefficient is 0.01875mV/K.

Fig 6 shows the variation V_{ref} when the R_x is varied from 1 Ω to 2.4k Ω . The relative variation V_{ref} is 2.79mv/k Ω at 27°C. So the worst case operation of the device is when R_x is 2.4k Ω and 1 Ω . In the table1, PSRR and TC are shown for different R_x .

Fig 7 shows variation of V_{ref} when temperature changes between 0°C to 80°C. Temperature coefficient of 0.1mV/K is obtained.

The D.C characteristics at 80 degrees are shown in Fig 8. The variation with V_{dd} is much worse in this case. The simulation demonstrated PSRR is 37dB.

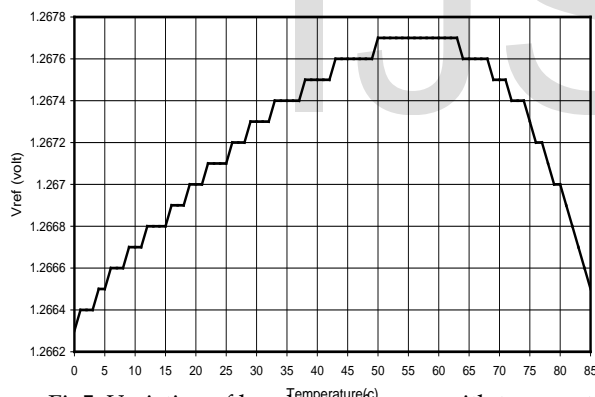


Fig5 .Variation of bandgap reference with temperature at $V_{dd}=3.3V$ and $R_x=900\Omega$

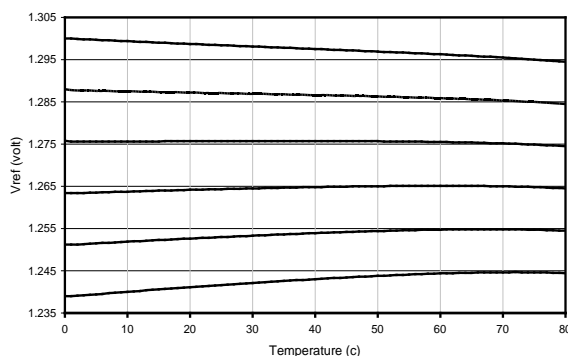


Fig6 .Variation of bandgap reference with temperature for $R_x=1\Omega$ to 2.4K Ω ($V_{dd}=3.3V$)

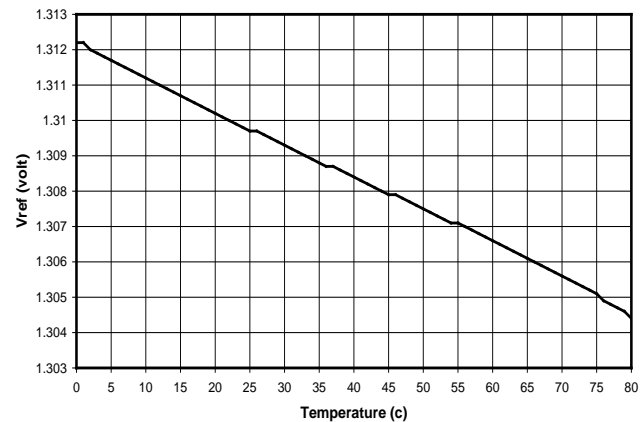


Fig7 .Variation of bandgap reference with temperature at $V_{dd}=3.3V$ and $R_x=2400\Omega$

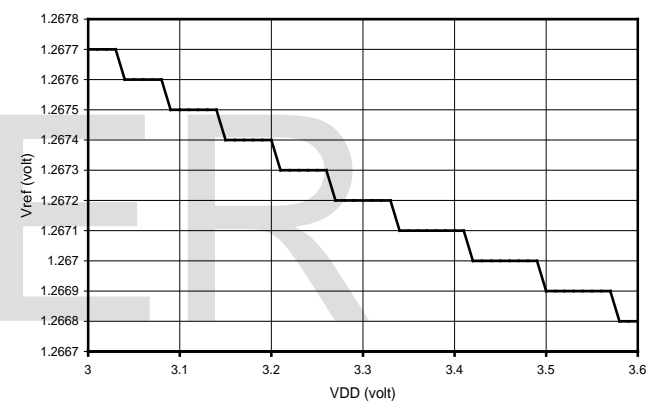


Fig8: Variation of the reference voltage with supply voltage at 27°C

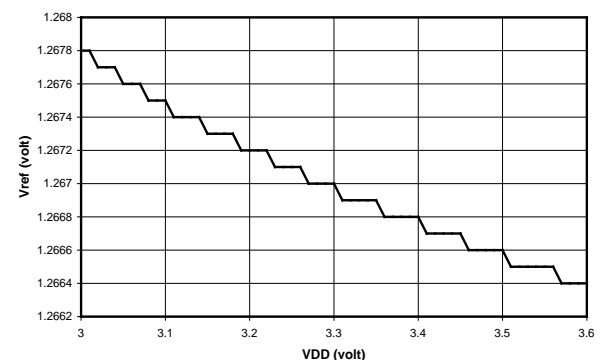


Fig 9: Variation with Supply Voltage at 80 C (absolute worst case)

TABLE 1
REFERENCE VOLTAGE OBTAINED UNDER DIFFERENT R_x

	$R_x=1\Omega$	$R_x=0.9k\Omega$	$R_x=2.4k\Omega$
PSRR(dB)	42	56	37
TC (ppm/°C)	13.1	10.84	15.01

TABLE 2
SUMMARY OF PERFORMANCE WITH AND WITHOUT Rx

	With Rx	Without Rx
Technology (μm)	0.35	0.35
Supply voltage range (Volt)	3.00-3.6	3.00-3.6
V_{REF} (Volt)	1.2672	1.2228
PSRR (dB)	56	60
Temperature coefficient (ppm/ $^{\circ}\text{C}$)	10.84	10.2
Integrated noise ($\mu\text{V}/\sqrt{\text{Hz}}$)	0.156	0.154
Load Regulation (50k Ω -120k Ω)	87.1 $\mu\text{V}/\Omega$	85.21 $\mu\text{V}/\Omega$

This circuit is simulated for FF, SS, FS and SF model. PSRR for FF, FS, SF and SS corner was 52dB, 55dB, 56dB and 60db and TC also was 15, 10, 50, and 20 ppm/C. These results show that FS is worse case for this circuit.

5 CONCLUSION

A bandgap reference with a current feedback mode has been designed. The circuit uses no external current sources and is designed to have a zero temperature coefficient at 27 $^{\circ}\text{C}$. The design is simulated implemented with 0.35 μm CMOS process. The circuit generates a variable reference voltage of 1.2380 until 1.3051. Table 2 shows the summary of performance of proposed circuit. The output voltage is 1.2659V at the nominal operating condition of 27 $^{\circ}\text{C}$ temperature and 3.3V supply voltage. It has a temperature coefficient of 0.0141mV/K from 0-804 $^{\circ}\text{C}$.

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